

REMARKS

Applicants thank the Examiner for the courtesy extended to Applicants' attorney during the interview held November 7, 2005, in the above-identified application. During the interview, Applicants' attorney explained the presently-claimed invention and why it is patentable over the applied prior art, and discussed other issues raised in the Office Action. The discussion is summarized and expanded upon below.

As recited in above-amended Claim 1, the present invention is a laser sintering powder comprising (a) at least one polyamide; (b) titanium dioxide particles, and (c) at least one flow aid, wherein the at least one polyamide is nylon-6,12, nylon-11, nylon-12, or mixtures thereof.

The rejection of Claims 1, 6, 7, 9, 10, 12, and 13 under 35 U.S.C. § 102(b) as anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as obvious over, JP 6-248088 (JP '088), is respectfully traversed. JP '088 discloses a process for making metallised powders without etching the surface of a resin powder for hydrophilicization or using a supported noble metal catalyst by attaching and fixing semi-conductor particles to resin powder, which involves attaching and fixing the semi-conductor particles to the resin powder. The metallised powders are disclosed as useful for electromagnetic shielding, wave absorbing, exothermic or electroconductive materials. JP '088 discloses a polyamide resin, *inter alia*, as an exemplary base resin [0006], and TiO<sub>2</sub>, *inter alia*, as an exemplary semi-conductor particle [0007], and as an Example, nylon 12 combined with TiO<sub>2</sub> [0015]. However, JP '088 neither discloses nor suggests the addition of a flow aid. Since the powders of JP '088 are then dispersed in a solution containing, *inter alia*, a metal precursor such as copper sulfate in the Example, to form metallised powders, there would be no reason to add the presently-recited component (c) to the powder of JP '088.

For all the above reasons, it is respectfully requested that this rejection be withdrawn.

The rejections of Claims 1, 4-10, 12, 13 and 23 under 35 U.S.C. § 102(b) as anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as obvious over, and of Claim 24 under 35 U.S.C. § 103(a) as obvious over, U.S. 4,689,364 (Mumcu et al), are respectfully traversed. Mumcu et al is from the same patent family as DE 3510687, described in the specification herein at page 6, line 6ff. Mumcu et al is drawn to the production of polyamide powders for the coating of metals (column 1, lines 23-24). The polyamide powders are obtained by a method involving precipitation of a mixture containing polyamide and titanium dioxide pigment (paragraph bridging columns 3 and 4). However, other than the above-discussed disclosure with regard to coating of metals, Mumcu et al disclose and suggest nothing with regard to any other utility, let alone one that would require the addition of a flow aid. Accordingly, it is respectfully requested that this rejection be withdrawn.

The rejection of Claims 8, 14, 15, 20, 21 and 24 under 35 U.S.C. § 103(a) as unpatentable over JP '088 in view of U.S. 6,211,266 (Weber et al), is respectfully traversed. The disclosures and deficiencies of JP '088 have been discussed above. Weber et al does not remedy these deficiencies. With special regard for Claim 8, even if the titanium dioxide used is that disclosed by Weber et al, the result would still not be the presently-claimed invention. With special regard for Claims 14, 15, 20 and 21, all drawn to a process for producing moldings or moldings so produced, JP '088 is drawn, as discussed above, to the formation of metallised powders for various utilities, none of which is disclosed as involving molding, let alone laser sintering molding. Thus, without the present disclosure as a guide, one skilled in the art would not use the metallised powders of JP '088, or the powders thereof prior to metallization, to produce a molding, let alone laser sintering molding. In addition, **submitted herewith** is an Information Disclosure Statement containing a copy of U.S. 6,136,948 (Dickens et al), which shows that selective laser sintering molding presents problems not found in other molding processes.

For all the above reasons, it is respectfully requested that this rejection be withdrawn.

The rejection of Claims 9-11 under 35 U.S.C. § 112, second paragraph, is respectfully traversed. Indeed, the rejection is now moot in view of the above-discussed amendment.

Accordingly, it is respectfully requested that this rejection be withdrawn.

Applicants gratefully acknowledge the Examiner's indication of allowability of Claims 18 and 19. Nevertheless, Applicants respectfully submit that all of the presently pending claims in this application are in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to pass this application to issue.

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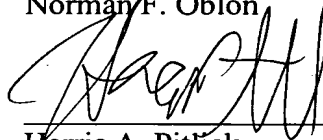
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